

Title (en)

RETAINING RING FOR HOLDING SEMICONDUCTOR WAFERS IN A CHEMICAL-MECHANICAL POLISHING DEVICE

Title (de)

HALTERING ZUM HALTEN VON HALBLEITERWAFERN IN EINER CHEMISCH-MECHANISCHEN POLIERVORRICHTUNG

Title (fr)

ANNEAU DE FIXATION DE PLAQUETTES EN SEMICONDUCTEURS DANS UN DISPOSITIF DE POLISSAGE PAR VOIE CHIMIQUE-MECANIQUE

Publication

**EP 1545836 A1 20050629 (DE)**

Application

**EP 03757898 A 20031001**

Priority

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Abstract (en)

[origin: US2004065412A1] A retaining ring to be fitted on a chemical mechanical polishing apparatus for semiconductor wafers is disclosed, the retaining ring comprising a carrier ring made of a first material and having fitting elements for fitting the carrier ring on the polishing apparatus; and a bearing ring comprising a plastic material, arranged concentrically on the carrier ring, the bearing ring resting with a first front side on a polishing surface of the polishing apparatus and being held on its side axially opposed to the first front side releasably, non-rotatably, with a positive and/or frictional connection and without adhesive on the carrier ring; wherein the first material has a higher rigidity than the plastic material of the bearing ring.

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**B24B 37/04**

IPC 8 full level

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CPC (source: EP KR US)

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